



ClockWorks™ 10GbE (156.25MHz), Ultra-Low Jitter, LVPECL Frequency Synthesizer

General Description

Block Diagram

The SM802121 is a member of the ClockWorks[™] family of devices from Micrel and provides an extremely low-noise timing solution for 10GbE Ethernet clock signals. It is based upon a unique patented RotaryWave[®] architecture that provides very-low phase noise.

The device operates from a 2.5V or 3.3V power supply and synthesizes an LVPECL output clock at 156.25MHz. The SM802121 accepts a 25MHz crystal or LVCMOS reference clock.

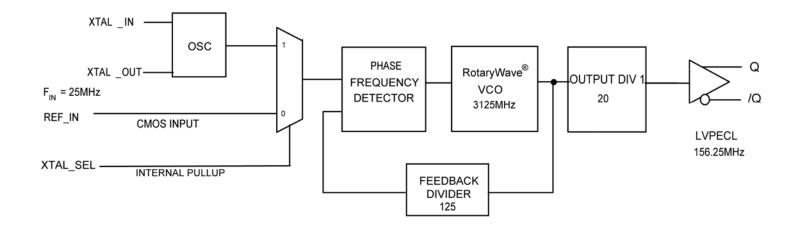
Data sheets and support documentation can be found on Micrel's web site at: <u>www.micrel.com</u>.

Features

- Generates one LVPECL clock outputs at 156.25MHz
- 2.5V or 3.3V operating range
- Typical phase jitter @ 156.25MHz (1.875MHz to 20MHz): 110fs
- Industrial temperature range
- Green, RoHS-, and PFOS- compliant
- Available in 24-pin 4mm × 4mm QFN package

Applications

• 10 Gigabit Ethernet



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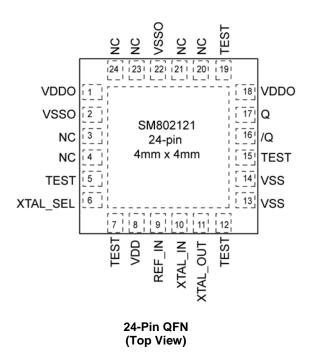
Ordering Information⁽¹⁾

Part Number	Marking	Shipping	Temperature Range	Package
SM802121UMG	802121	Tube	–40°C to +85°C	24-Pin QFN
SM802121UMGTR	802121	Tape and Reel	–40°C to +85°C	24-Pin QFN

Note:

1. Devices are Green, RoHS-, and PFOS- compliant.

Pin Configuration



Pin Description

Pin Number	Pin Name	Pin Type	Pin Level	Pin Function	
16, 17	/Q, Q	O, (DIF)	LVPECL	Differential Clock Output 156.25MHz.	
1, 18	VDDO	PWR		Power Supply for Output.	
2, 22	VSSO	PWR		Power Supply Ground for Output.	
6	XTAL_SEL	I, (SE)	LVCMOS	Selects PLL Input Reference Source (0 = REF_IN, 1 = XTAL, 45K Ω pull-up).	
3, 4, 20, 21, 23, 24	NC			No Connect. Do not connect anything to these pins.	
5, 7, 12, 15, 19	TEST			Factory Test Pins. Do not connect anything to these pins.	
8	VDD	PWR		Core Power Supply.	
13, 14	VSS (Exposed Pad)	PWR		Core Power Supply Ground. The exposed pad must be connected to the VSS ground plane.	
9	REF_IN	I, (SE)	LVCMOS	Reference Clock Input.	
10	XIN	I, (SE)	crystal	Crystal Reference Input. No load caps needed. (See Fig. 5)	
11	XOUT	O, (SE)	crystal	Crystal Reference Output. No load caps needed. (See Fig. 5)	

Application Information

Input Reference

When operating with a crystal input reference, do not apply a switching signal to REF_IN.

Crystal Layout

Keep the layers under the crystal as open as possible and do not place switching signals or noisy supplies under the crystal. Crystal load capacitance is built inside the die so no external capacitance is needed. See the *Selecting a quartz crystal for the Clockworks Flex I Family of Precision Synthesizers* application note for further details.

Contact Micrel's HBW applications group if you need assistance on selecting a suitable crystal for your application at <u>hbwhelp@micrel.com</u>

Truth Table

XTAL_SEL	INPUT
0	REF_IN
1	XTAL

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V _{DD} , V _{DDO})	+4.6V
Input Voltage (V _{IN})	–0.50V to V _{DD} + 0.5V
Lead Temperature (soldering, 20s)	
Case Temperature	115°C
Storage Temperature (T _s)	65°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V _{DD} , V _{DDO})	+2.375V to +3.465V
Ambient Temperature (T _A) Junction Thermal Resistance ⁽³⁾	40°C to +85°C
Junction Thermal Resistance ⁽³⁾	
QFN (θ_{JA})	
Still-Air	
QFN (ψ _{JB})	
Junction-to-Board	

DC Electrical Characteristics⁽⁴⁾

V_{DD} = V_{DDO} = 3.3V ±5% or 2.5V ±5%
V_{DD} = 3.3V ±5%, $V_{\text{DDO}}\text{=}$ 3.3V ±5% or 2.5V ±5%

 $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C.$

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V_{DD}, V_{DDO}	2.5V Operating Voltage		2.375	2.5	2.625	V
V _{DD} , V _{DDO}	3.3V Operating Voltage		3.135	3.3	3.465	V
I _{DD}	Supply Current V _{DD} + V _{DDO}	XTAL_SEL = 0; REF_IN source, outputs open		78	100	mA
I _{DD}	Supply Current V _{DD} + V _{DDO}	XTAL_SEL = 1; CRYSTAL source, outputs open		88	114	mA

LVPECL DC Electrical Characteristics⁽⁴⁾

 V_{DD} = V_{DDO} = 3.3V ±5% or 2.5V ±5%

 V_{DD} = 3.3V $\pm 5\%,\,V_{DDO}$ = 3.3V $\pm 5\%$ or 2.5V $\pm 5\%$

 $T_A = -40^{\circ}C$ to $+85^{\circ}C$. $R_L = 50\Omega$ to $V_{DDO} - 2V$

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
V _{OH}	Output High Voltage		$V_{\text{DDO}} - 1.145$	$V_{\text{DDO}}-0.97$	$V_{\text{DDO}}-0.845$	V
V _{OL}	Output Low Voltage		$V_{\text{DDO}} - 1.945$	V _{DDO} - 1.77	V _{DDO} - 1.645	V
V _{SWING}	Output Voltage Swing		0.6	0.8	1.0	V

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB.
- 4. The circuit is designed to meet the AC and DC specifications shown in the above table(s) after thermal equilibrium has been established.

LVCMOS (XTAL_SEL) DC Electrical Characteristics⁽⁴⁾

 V_{DD} = 3.3V ±5%, or 2.5V ±5%, T_A = -40°C to +85°C.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
VIH	Input High Voltage		2		V _{DD} + 0.3	V
V _{IL}	Input Low Voltage		-0.3		0.8	V
I _{IH}	Input High Current	$V_{DD} = V_{IN} = 3.465V$			5	μA
IIL	Input Low Current	V _{DD} = 3.465V, V _{IN} = 0V	-150			μA

REF_IN DC Electrical Characteristics⁽⁴⁾

 V_{DD} = 3.3V ±5%, or 2.5V ±5%, T_A = -40°C to +85°C.

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
VIH	Input High Voltage		1.1		V _{DD} + 0.3	V
VIL	Input Low Voltage		-0.3		0.6	V
lini	Input Current	$XTAL_SEL = V_{IL}, V_{IN} = 0V \text{ to } V_{DD}$	-5		5	μA
IIN	I _{IN} Input Current	$XTAL_SEL = V_{IH}, V_{IN} = V_{DD}$		20		μA

Crystal Characteristics

Parameter	Condition	Min.	Тур.	Max.	Units		
Mode of Oscillation	10pF Load	Fu	Fundamental, Parallel Resonant				
Frequency			25		MHz		
Equivalent Series Resistance (ESR)				50	Ω		
Shunt Capacitor (C0)			1	5	pF		
Correlation Drive Level			10	100	uW		

AC Electrical Characteristics^(4, 5)

 V_{DD} = V_{DDO} = 3.3V $\pm 5\%$ or 2.5V $\pm 5\%$

 V_{DD} = 3.3V ±5%, V_{DDO} = 3.3V ±5% or 2.5V ±5%

 $T_A = -40^{\circ}C$ to $+85^{\circ}C$. $R_L = 50\Omega$ to $V_{DDO} - 2V$

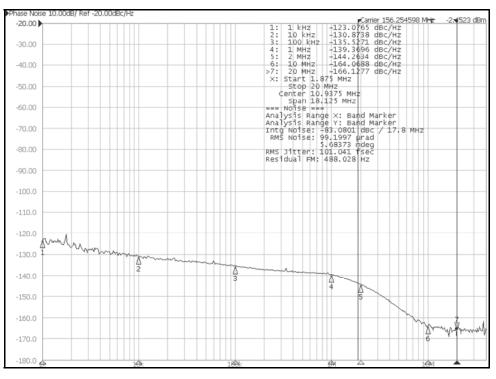
Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
F _{OUT}	Output Frequency			156.25		MHz
F _{REF}	Reference Input Frequency			25		MHz
T _R /T _F	LVPECL Output Rise/Fall Time	20% - 80%	80	175	350	ps
ODC	Output Duty Cycle		48	50	52	%
TLOCK	PLL Lock Time				20	ms
T _{jit} (∅)	RMS Phase Jitter ⁽⁶⁾	156.25MHz Integration Range (1.875MHz – 20MHz) Integration Range (12kHz – 20MHz)		110 250		fs
	Spurious Noise Components	6.25MHz		-75		dBc

Notes:

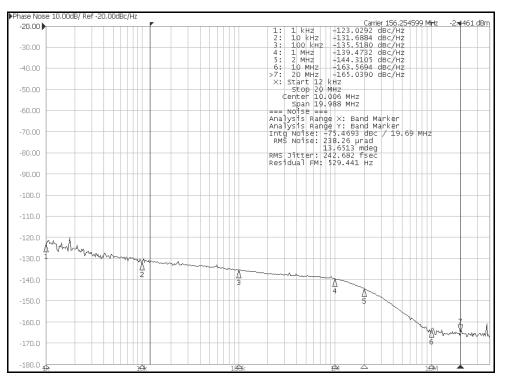
5. All phase-noise measurements were taken with an Agilent 5052B phase-noise system.

6. Measured using a 25MHz crystal as the input reference source. If using an external reference input, use a low phase noise source. With an external reference, the phase noise will follow the input source phase noise up to about 1MHz offset.

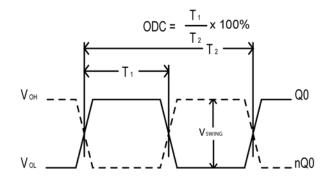
Phase Noise Plots (XTAL Source)

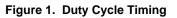


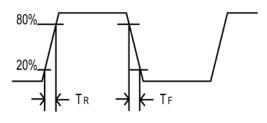
Phase Noise Plot: 156.25MHz, 1.875MHz – 20MHz 101fS













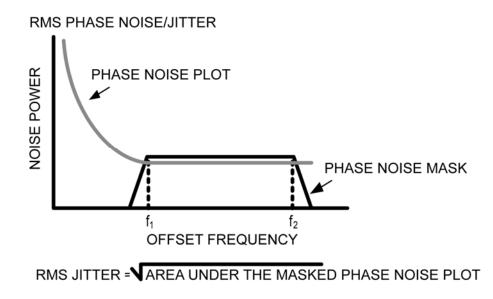


Figure 3. RMS Phase/Noise Jitter

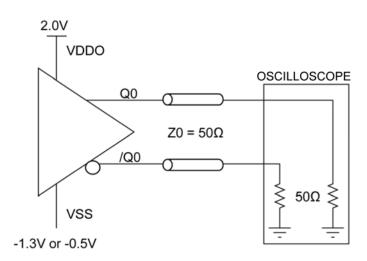


Figure 4. LVPECL Output Load and Test Circuit

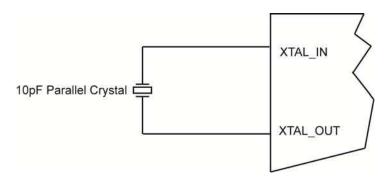
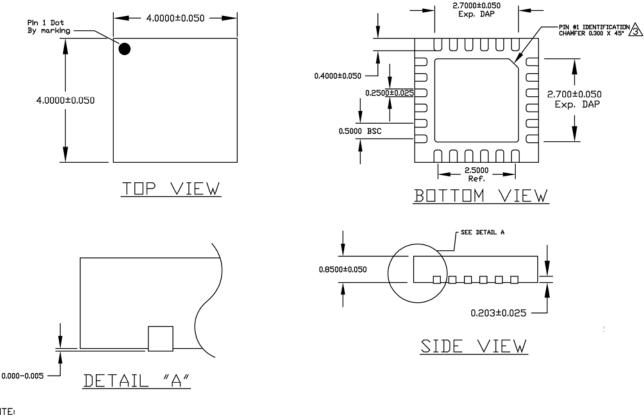


Figure 5. Crystal Input Interface

Package Information



NOTE: 1. ALL DIMENSIONS ARE IN MILLIMETERS (mm).

- THE PIN#1 IDENTIFIER MUST EXIST ON THE TOP SURFACE 2. OF PACKAGE BY USING IDENTIFICATION MARK OR OTHER FEATURE OF PACKAGE BODY.
- 3. CHAMFER STYLE PIN 1 IDENTIFIER ON BOTTOM SIDE

24-Pin Package Type

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